

ABSTRACT OF THE DISCLOSURE

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A multiple semiconductor chip (multi-chip) module for use in high-power applications includes at least a power semiconductor chip and a control semiconductor chip mounted on an electrically conductive heat sink. The power semiconductor chip may be a

5 Silicon-On-Insulator (SOI) device and the control semiconductor chip may be a semiconductor device having a substrate connected to ground potential. The power semiconductor chip and the control semiconductor chip are directly mounted on the electrically

10 insulation layer in order to obtain a multi-chip module which is simple and economical to manufacture, and which offers superior performance characteristics.